

07-12-2001



Atty. Docket No.: 2332-0107P

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RECORDATION FORM COVER SHEET

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

11040 U.S. PTO
09/893650
06/29/01

1. Name of conveying party(ies):
CHO, Heung Jae and PARK, Dea Gyu
Additional name(s) of conveying party(ies) attached?
YES NO

2. Name and address of receiving party(ies)
Name: HYNIX SEMICONDUCTOR INC.
Internal Address:
Street Address: San 136-1, Ami-ri, Bubal-eub, Ich'on
City: Kyoungki-do State: ZIP:
Country: KOREA Postal Code:
Additional name(s) & address(es) attached? YES NO

3. Nature of conveyance:
Assignment Merger
Security Agreement Change of Name
Other:

Execution Date: June 8, 2001

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:
June 8, 2001
A. Patent Application No(s). NEW
B. Patent No.(s).
Additional numbers attached? YES NO

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP
Street Address: P.O. BOX 747
City: FALLS CHURCH State: VA ZIP: 22040-0747
Country: USA

6. Total No. of applications/patents involved: ONE (1)
7. Total fee (37 C.F.R. § 3.41): \$40.00
Enclosed
Authorized to be charged to deposit account, if no fee attached.
8. Deposit account number: 02-2448
(Attach triplicate copy of this page if paying by deposit account)

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Gary D. Yacura, #35,416
Name of Person Signing/Reg. No.
Signature
June 29, 2001
Date

Total number of pages including cover sheet, attachments, and document: THREE (3)

GDY/sl

07/05/2001 VTRUENGL 00000040 09853650
04 PD:081 02.00 DP

(Rev. 01/11/01)

BIRCH, STEWART, KOLASCH & BIRCH, LLP

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. NEW

Filed June 29, 2001

**Insert Name(s)
of Inventor(s)**

WHEREAS, Heung Jae CHO Dea Gyu PARK

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

**Insert Title
of Invention**

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME USING DAMASCENE PROCESS

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

**Insert Date
of Signing of
Application**

on June 8, 2001 _____; and

**Insert Name
of Assignee**

WHEREAS, Hynix Semiconductor Inc.

**Insert Address
of Assignee**

of San 136-1, Ami-ri, Bubal-eub, Ich'on, Kyoungki-do, Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

**CHECK BOX
IF APPROPRIATE**

in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

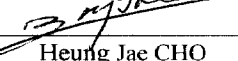
The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date June 8, 2001,

Name of Inventor 
(signature) Heung Jae CHO

Date June 8, 2001,

Name of Inventor 
(signature) Dea Gyu PARK

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)